

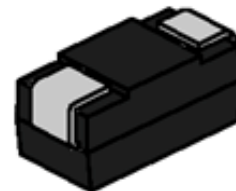


## CP4200Sx Series TSS

Rev.4.2

### DESCRIPTION:

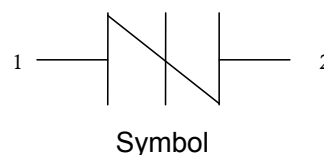
CP4200Sx series are a type of semiconductor component. They are designed to protect baseband equipment from damaging overvoltage transients.



SMB

### FEATURES:

- Low profile package.
- Low on-state voltage.
- Excellent capability of absorbing transient surge.
- Quick response to surge voltage (ns Level).
- Eliminates overvoltage caused by fast rising transients.
- Moisture sensitivity level: Level 1.
- Non degenerative.

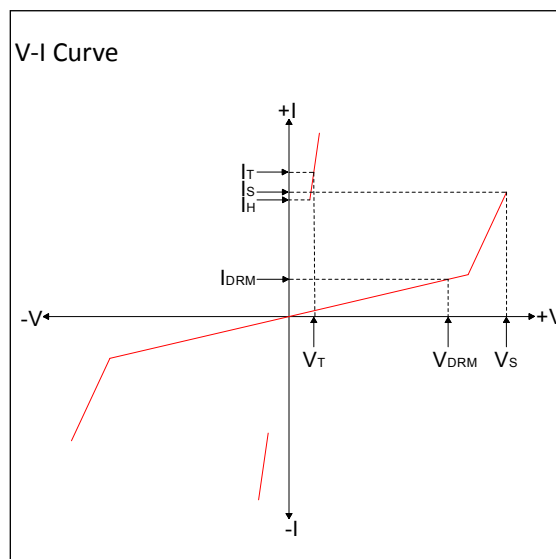


### ABSOLUTE MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$ , RH=45%-75%, unless otherwise noted)

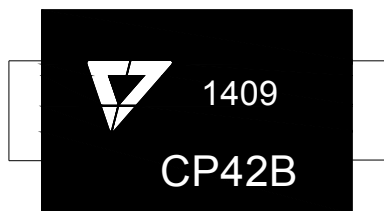
Parameter	Symbol	Value	Unit
Storage temperature range	$T_{STG}$	-60 to +150	$^{\circ}\text{C}$
Operating junction temperature range	$T_J$	-40 to +125	$^{\circ}\text{C}$
Repetitive peak pulse current	$I_{PP}$	see next table	A

### ELECTRICAL CHARACTERISTICS ( $T_A=25^{\circ}\text{C}$ )

Symbol	Parameter
$V_{DRM}$	Peak off-state voltage
$I_{DRM}$	Off-state current
$V_S$	Switching voltage
$I_S$	Switching current
$V_T$	On-state voltage
$I_T$	On-state current
$I_H$	Holding current
$C_O$	Off-state capacitance



MARKING



CP42B : Device Marking Code  
1409: In ninth week, 2014

ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C, continued)

Part Number	I <sub>DRM</sub> @V <sub>DRM</sub>		V <sub>S</sub> <sup>①</sup> @I <sub>S</sub>		V <sub>T</sub> @ I <sub>T</sub>		I <sub>H</sub>	C <sub>O</sub> <sup>②</sup>	Marking
	μA	V	V	mA	V	A	mA	pF	
	max		max	max	max	max	max	max	
CP4200SB	1	400	520	800	4	2.2	100	35	CP42B
CP4200SC	1	400	520	800	4	2.2	100	35	CP42C
CP4200SD	1	400	520	800	4	2.2	100	40	CP42D

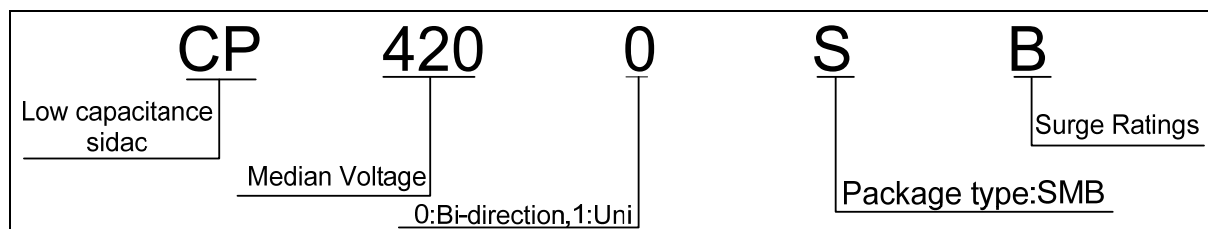
① V<sub>S</sub> is measured at 100KV/s

② Off-state capacitance is measured in V<sub>DC</sub>=2V, V<sub>RMS</sub>=1V, f=1MHz

SURGE RATINGS

Surge peak	Series		
	B	C	D
	I <sub>PP</sub> (A) min	I <sub>PP</sub> (A) min	I <sub>PP</sub> (A) min
5/320μs (10/700μs)	100	150	200
8/20μs (1.2/50μs)	250	400	600
2/10μs	250	500	800
10/1000μs	80	100	200

ORDERING INFORMATION



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see FIG.2)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ ) (Liquidus)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C

FIG.1: tr × td pulse waveform

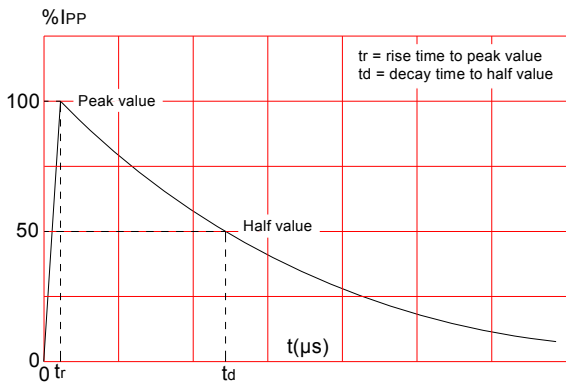


FIG.2: Reflow condition

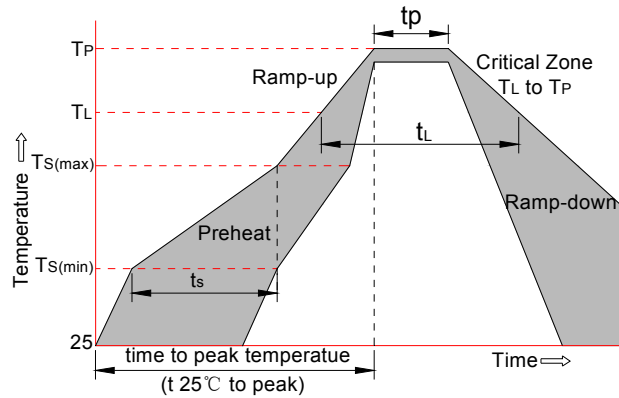


FIG.3: Normalized Vs change vs. junction temperature

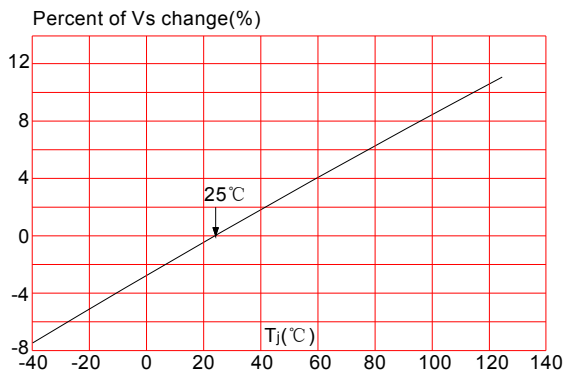
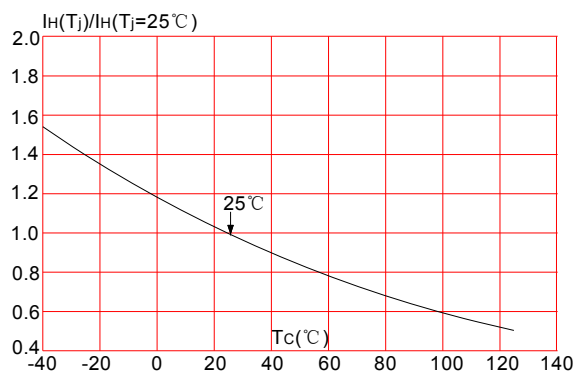
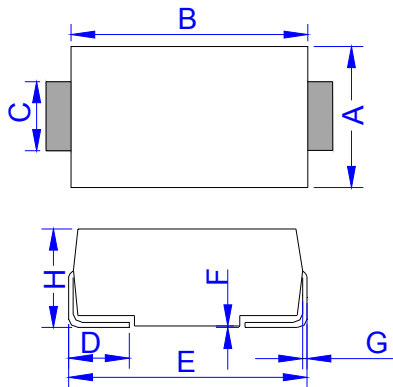


FIG.4: Normalized DC holding current vs. case temperature



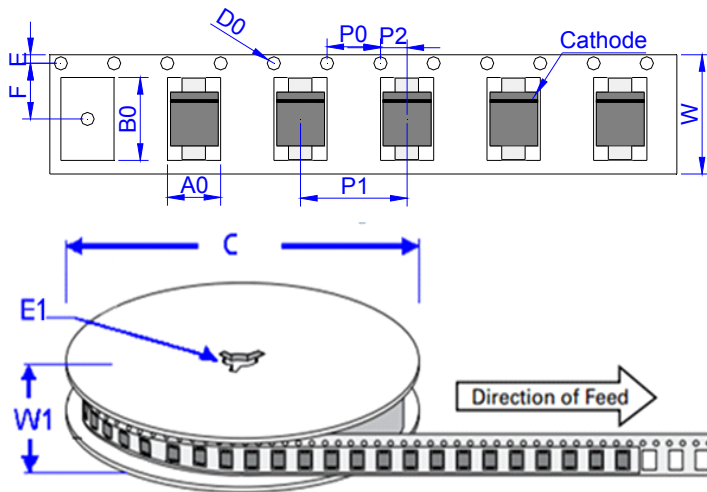
PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	3.94	0.130	0.155
B	4.30	4.80	0.169	0.189
C	1.90	2.20	0.075	0.087
D	0.95	1.52	0.037	0.060
E	5.20	5.60	0.205	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.10	2.40	0.083	0.094
J	2.20		0.087	
K		2.60		0.102
L	2.30		0.091	


TAPE AND REEL SPECIFICATION-SMB



Ref.	Dimensions	
	Millimeters	Inches
A0	3.76 ± 0.3	0.148 ± 0.012
B0	5.69 ± 0.3	0.224 ± 0.012
C	330.0	13.0
D0	1.55 ± 0.1	0.061 ± 0.004
E	1.75 ± 0.2	0.069 ± 0.008
E1	13.3 ± 0.3	0.524 ± 0.012
F	5.5 ± 0.2	0.217 ± 0.008
P0	4.00 ± 0.2	0.157 ± 0.008
P1	8.00 ± 0.2	0.3145 ± 0.008
P2	2.00 ± 0.2	0.079 ± 0.008
W	12.0 ± 0.2	0.472 ± 0.008
W1	15.7 ± 2.0	0.618 ± 0.079

OUTLINE	UNIT WEIGHT (g/PCS) typ.	REEL (PCS)	PER CARTON (PCS)	REEL DIAMETERS (mm)
TAPING	0.098	3,000	48,000	330

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co.,Ltd assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement. Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document is the 4.2nd version which is made in 31-Jan.-2018. This document supersedes and replaces all information previously supplied.

 is a registered trademark of Jiangsu JieJie Microelectronics Co.,Ltd.  
Copyright©2018Jiangsu JieJie Microelectronics Co.,Ltd. Printed All rights reserved.